



KBPG Material Safety Data Sheet

Material Content Declaration					
Material name	Substance name e.g. Copper (Cu).	CAS no., if known	Substance mass (mg)	% OF Weight (%)	ppm Of Total Weight
Lead Frame 48.76%	Copper (Cu)	7440-50-8	569.41	99.81	486,675.2
	Phosphorus (P)	7723-14-0	0.23	0.04	196.6
	Iron (Fe)	7439-89-6	0.86	0.15	735.0
	Total		570.50		
Solder Paste 1.44%	Lead (Pb)	7439-92-1	15.54	92.5	13,282.1
	Tin (Sn)	7440-31-5	0.84	5.0	717.9
	Silver (Ag)	7440-22-4	0.42	2.5	359.0
	Total		16.80		
Chip 1.01%	Silicon (Si)	7440-21-3	11.05	93.48	9,444.4
	Nickel (Ni)	7440-02-0	0.68	5.78	581.2
	Gold (Au)	7440-57-5	0.01	0.20	8.5
	Lead (Pb)	7439-92-1	0.06	0.54	51.3
	Total		11.80		
Molding 48.64%	Silica	14808-60-7	398.37	70	340,487.2
	Epoxy Resin	24969-06-0	85.37	15	72,965.8
	Phenol Resin	9003-35-4	56.91	10	48,641.0
	Antimonytrioxide	1309-64-4	11.38	2.00	9,726.5
	Carbon Black	1333-86-4	5.69	1.00	4,863.2
	Brominated Resin	40039-93-8	11.38	2.00	9,726.5
	Total		569.10		
Plating 0.15%	Tin (Sn)	7440-31-5	1.80	100.00	1,538.5
	Total		1.80		
	Total mass (mg)		1,170.00		